DOCUMENT TYPE: PLP

DOCUMENT ID #: 90-100271

REVISION: A-000

DOCUMENT TITLE: PACKAGE LAND PATTERN, [F1733F+1F / F1733

EFFECTIVE DATE: 07/29/2024

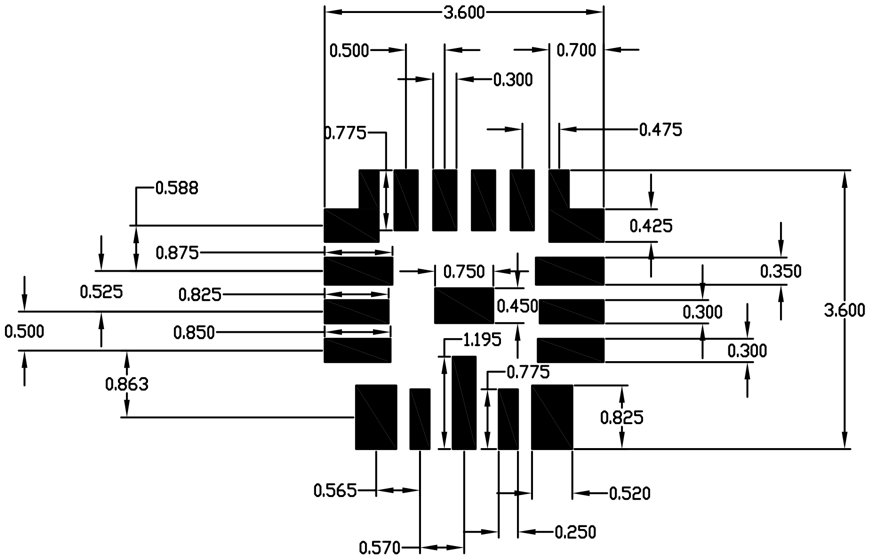
EXPIRATION DATE:

CHANGE NUMBER: 1213824

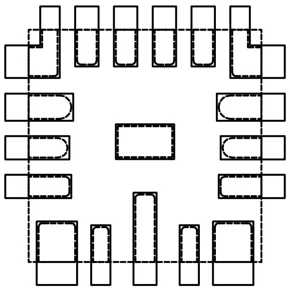
ORIGINATOR: Aurelio Giron Jr.

REASON FOR CHANGE:
INITIAL RELEASE

RECOMMENDED LAND PATTERN



PACKAGE OVERLAY



NOTES:

1. REFERENCE PKG. OUTLINE: 21-100774 / 21-100775
2. LAND PATTERN COMPLIES TO: IPC7351A.
3. TOLERANCE: +/- 0.02 MM.
4. ALL DIMENSIONS APPLY TO LEADED, PbFREE PACKAGES.
5. ALL DIMENSIONS IN MM.

-DRAWING NOT TO SCALE-

ANALOG
DEVICES

This document (including dimensions, notes & specs) is a recommendaton based on typical circuit board manufacturing parameters. Since land pattern design depend on many factors unknown to Analog Devices Inc. (eg. user's board manufacturing specs), user must determine suitability for use. This document is subject to change without notice.
Contact technical support at https://www.analog.com/en/support for further questions.

TITLE:
PACKAGE LAND PATTERN,
[F1733F+1F / F1733FY+1F] FC2QFN

APPROVAL	DOCUMENT CONTROL NO.	REV.	
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REVISION HISTORY

REV	CHANGES MADE	DATE	INIT.
A	CN 1213824. INITIAL RELEASE	07/29/24	AG